

Resistive technologies for Time Projection Chambers

NA61++/SHINE: Physics opportunities from ions to pions

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for the CEA/IRFU neutrino group

CEA-Saclay/DRF-IRFU-DPhP

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Irfu

Institut de recherche
sur les lois fondamentales
de l'Univers

Commissariat à l'énergie atomique et aux énergies alternatives French Alternative Energies and Atomic Energy Commission



The CEA is a public research organization

Key figures (2020)



> 20 000
employees



5
billion euros
(EVA and defense)



> 5 000
publications



> 440
European
Projects



Digital
Transition



Remediation and
dismantling

Headquarter - Paris

Research Centers

- 2 Cadarache (17)
- 3 Gif-sur-Yvette (91)
- 4 DAMA - Saclay (91)
- 6 Comptonnay (30)
- 7 Marcoule (26)
- 8 Paris Saclay (91)
- 9 Fontenay-aux-Roses (92)
- 10 Saclay (91)
- 11 Saclay (91)

- CEA Tech Regional hubs
- 11 Bretagne (29)
- 12 Grand Est (54)
- 13 Hauts-de-France (59)
- 14 Nouvelle-Aquitaine (87)
- 15 Occitanie Pyrénées-Méditerranée (31)
- 16 Pays de la Loire (44)
- 17 Région Sud PACA (Cantaloup et Gardanne)



Fundamental
Research



Defense
and Security



Energies



Healthcare
technologies



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GANIL

Département GANIL
unité de gestion
des personnels CEA
affectés au GIE
Grand accélérateur
national d'ions lourds

DPhP

Département
de physique
des particules

DPhN

Département
de physique
nucléaire

DAP-AIM

Département
d'astrophysique
UMR - AIM

DEDIP

Département
d'électronique,
détecteurs
et informatique
pour la physique

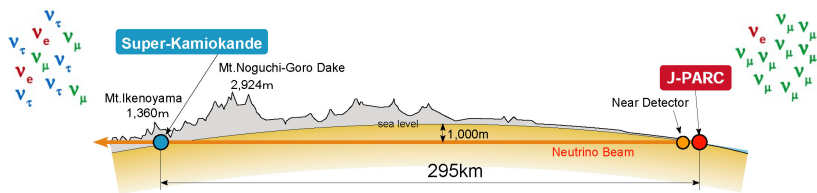
DIS

Département
d'ingénierie
des systèmes

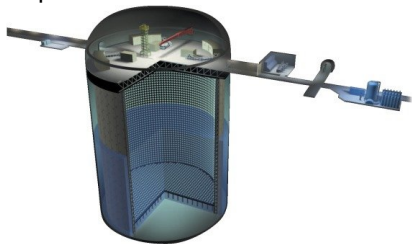
DACM

Département
des accélérateurs,
de cryogénie
et de magnétisme

Tokai-to-Kamioka: T2K long-baseline experiment

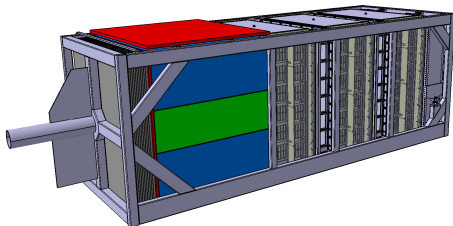


- ▶ Far detector: Water-Cherenkov Super-Kamiokande



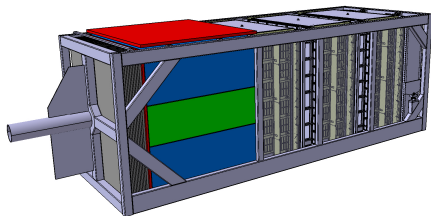
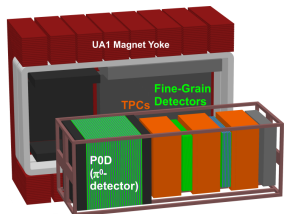
- ▶ Upgrade planned to T2HK
SK to be replaced by HK

- ▶ Several near detectors:
INGRID and ND280



- ▶ Upgrade of ND280 ongoing
P0D \Rightarrow sFGD + HA-TPCs

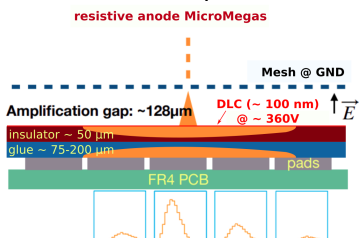
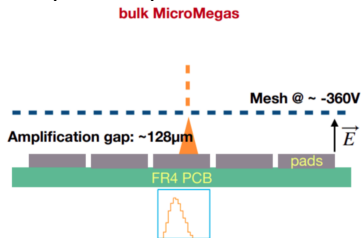
TPCs for the near detector of T2K-ND280



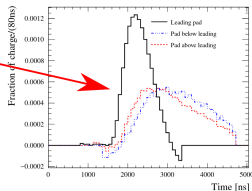
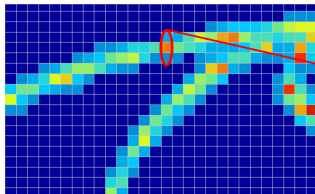
- ▶ **1998:** TPC studies conducted for ILC with Micromegas R&D
- ▶ **2009:** 3 vertical TPCs with 72 bulk Micromegas ($\sim 9 \text{ m}^2$)
- ▶ **2017:** Encapsulated Resistive Anode bulk Micromegas (ERAM) proposed for T2K ND280-Upgrade ($\sim 5 \text{ m}^2$)
- ▶ **2023:** Installation of ERAMs in ND-280
- ▶ **Future:** Growing community around resistive Micromegas technology, **promising** and **innovative** technology for future experiments

Encapsulated Resistive Anode bulk Micromegas (ERAM)

- ▶ Bulk Micromegas, mature and mastered technology
- ▶ New resistive Diamond-Like Carbon provides spark protection
- ▶ Charge spreading over multiple pads (ILC-TPC R&D) improves spatial resolution with cost-effective pad size



$$\sigma_r = \sqrt{\frac{2t}{RC}} \quad \left\{ \begin{array}{l} t \approx \text{shaping time (few 100 ns)} \\ RC_{[ns/mm^2]} = \frac{180 R_{[\text{M}\Omega/\blacksquare]}}{\frac{d_{[\mu m]}}{175}} \end{array} \right.$$



ERAMs prototyping and development steps

CERN/T9 test beam

D. Attié et al. NIM A 984, (2020), 163286

[doi:10.1016/j.nima.2019.163286](https://doi.org/10.1016/j.nima.2019.163286)

DESY test beam

D. Attié et al. NIM A 1025, (2022), 1661109

[doi:10.1016/j.nima.2019.166109](https://doi.org/10.1016/j.nima.2019.166109)

ERAM-01 @ DESY 2021

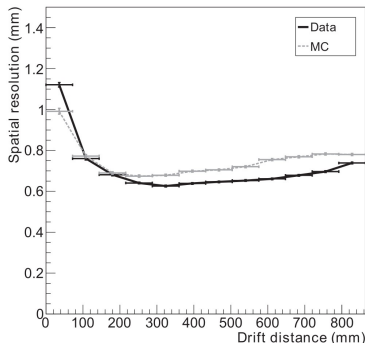
½ TPC mockup @ CERN/T10 sept. 2022

	2018 MM0-DLC#	2019 MM1-DLC1 & 2	2020 ERAM-P1 & P2	Production ERAM-xx (ERAM-01-28)
Readout PCB	Original T2K-TPC	HA-TPC V1 +ARC FEE	HA-TPC V2 +final FEE V1	HA-TPC V2 +final FEE V2
Size	34 × 36 cm ²	34 × 42 cm ²		
Pad size	6,85 × 9,65 mm ²	10,09 × 11,18 mm ²		
Number of pads	1728 (48 × 36)	1152 (32 × 36)		
DLC resistivity (MΩ/■)	~2,5 (original foil)	0,32-0,44 (foils) 0,2-0,27 (on detector)	0,28-0,40 (foils) 0,15-0,22 (on detector)	~1 (foils) / ~0.28-0,4 (det.) Top TPC: 1-1.5 (foils) After baking: 0,4-0,55
RC _{design} [ns/mm ²]	~260	50 < RC < 70	15 < RC < 23	35 < RC < 50
RC _{data} [ns/mm ²]		X-ray scan to process		102 < RC < 145 (this talk)
Insulation layer 50 μm APICAL +	200 μm glue	75 μm glue	200 μm glue	150 μm glue
Spatial resolution (μm) Beam (Horizontal tracks) Cosmics	300 (0T)	MM1-DLC1 200 (0 or 0.2T) 700 (MM1-DLC2, @370V)	300-350 (ERAM-Px @370V)	@ DESY 07/ 21 380-300 (ERAM-01)

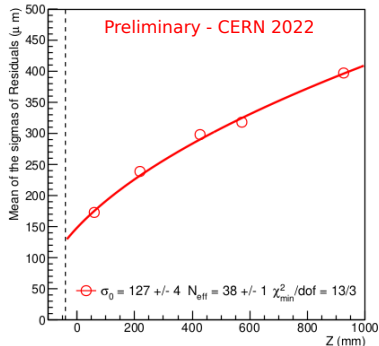
- ▶ RC_{design} from measured R and calculated C
- ▶ Main parameters changing during prototyping:
DLC resistivity and insulation layer thickness
- ▶ Target performances reached with all designs

ND280-Upgrade TPCs performance requirements

▶ Current ND280 TPCs



▶ ERAMs at CERN-T10



▶ Momentum reconstruction:

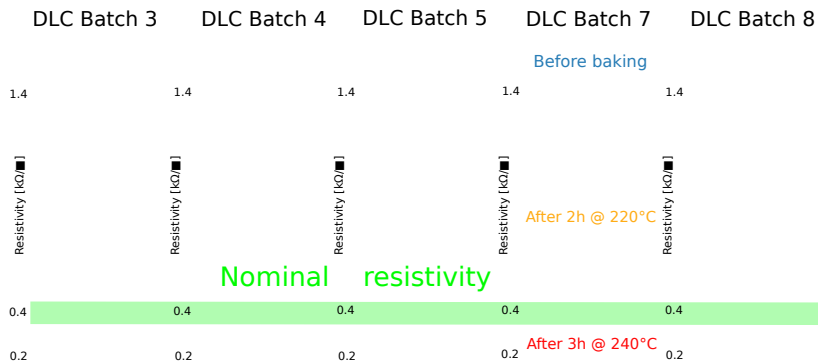
- Relatively loose requirements for ND280-Upgrade: **10% @ 1GeV**
- Factor of 3+ improvement with RC and granularity tuning \Rightarrow **flexibility**

▶ Particle identification through dE/dx

- Energy resolution: $\sim 10\%$ (PID: 45% larger dE/dx for e^- than μ/π)

▶ **Know-how** in detector building **and longevity over time demonstrated**

DLC foil selection for ERAMs



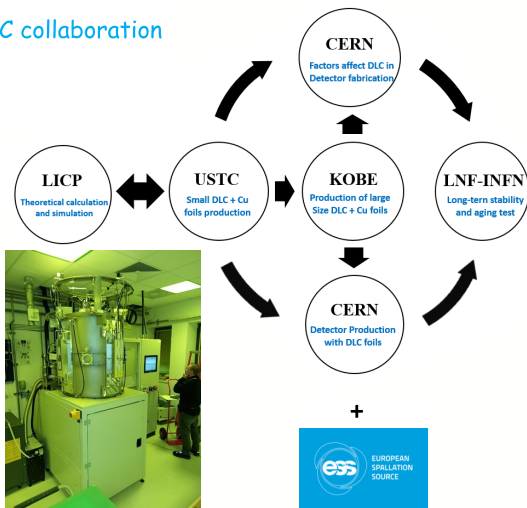
- ▶ Batch 4 with nominal resistivity \Rightarrow 9 final detectors
- ▶ Batch 3 and 5 with half nominal resistivity \Rightarrow Prototypes
- ▶ Batches 7 and 8 needed 2 bakings to provide nominal resistivity \Rightarrow \sim 8 final detectors
- ▶ 21/32 final detectors produced

CERN EP-DT-DD Micro-Pattern Technologies service

Talk by Rui de Oliveira at the MPGD 2022 conference

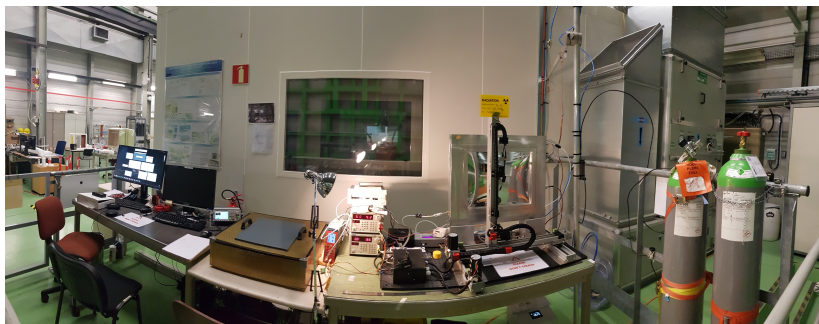
DLC collaboration

- Title of project:** *DLC based electrodes for future resistive MPGDs*
- Contact person:** *name: Yi Zhou
address: Jinchai Road No.96, Hefei, Anhui, P.R.China, 23
telephone number: +86-551-63607940
e-mail: zhouyi@mail.ustc.edu.cn*
- RD51 Institutes:**
- 1. State Key Laboratory of Particle Detection and Electron
University of Science and Technology of China,**
contact person: Yi Zhou
e-mail: zhouyi@mail.ustc.edu.cn
 - 2. Kobe University,**
contact person: Atsuhiko Ochi
e-mail: ochi@kobe-u.ac.jp
 - 3. CERN**
contact person: Rui de Oliveira
e-mail: Rui.de.Oliveira@cern.ch
 - 4. Laboratori Nazionali di Frascati dell'INFN**
contact person: Giovanni Bencivenni
e-mail: Giovanni.Bencivenni@lnf.infn.it
- Ext. Collaborators:**
- 1. State Key Laboratory of Solid Lubrication,
Lanzhou Institute of Chemical Physics, Chinese Academy**
contact person: Lunlin Shang
e-mail: shangll@lscps.cn



- ▶ In general, key partnership with MPT workshop for ERAM production
- ▶ World renowned expertise on MPGD/PCBs, new sputtering equipment
- ▶ Promising sputtering results $\Rightarrow \sim 10\%$ resistivity homogeneity achieved

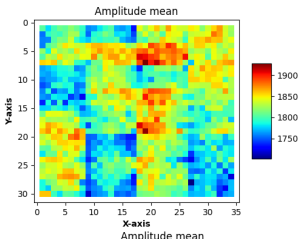
ERAM characterisation test bench



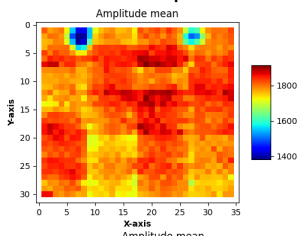
- ▶ All ERAMs individually characterised (1 week/ERAM)
- ▶ Signal pulsed on mesh without amplification
- ▶ Effective gain (ERAM * FE) and energy resolution @ 5.9 keV measurement on each pad with ERAM at nominal HV
- ▶ HV scan (330 - 360 V) in the center (gain tuning)
- ▶ Remote shifting organised with local hardware support

Pulsing of the ERAM mesh

ERAM-30

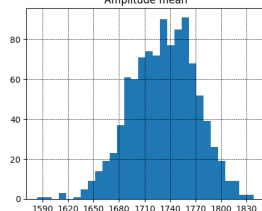
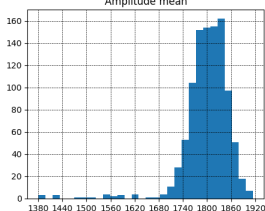
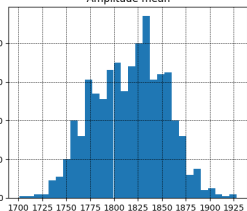
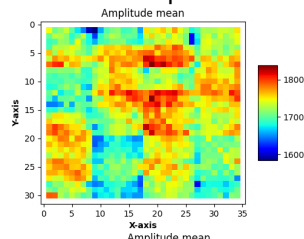


Before repair



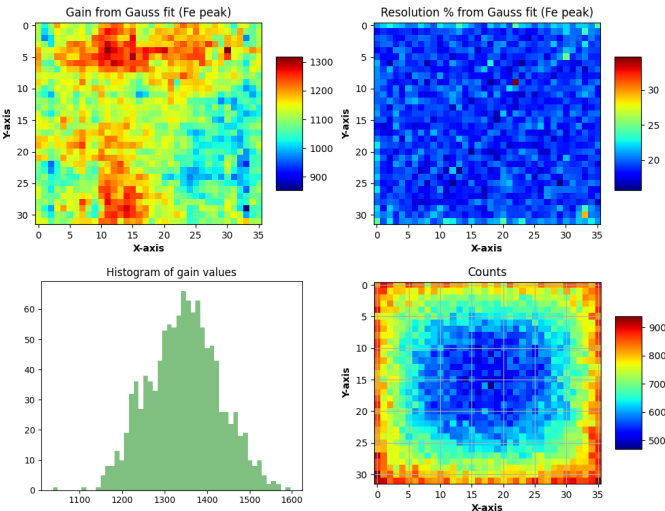
ERAM-20

After repair

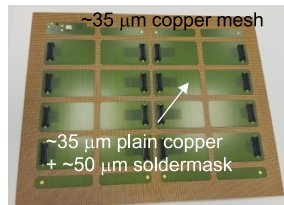


- ▶ Quality control step to **detect major defects** before mechanics gluing
- ▶ Mesh pulsed with a 1 kHz, 300 mV square signal
- ▶ Response of the **whole detector in one test**

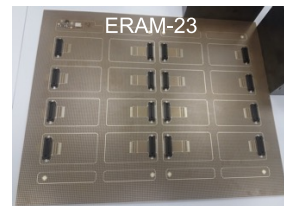
Gain scan of ERAM-30 with ^{55}Fe X-rays



All ERAMs PCB but 23, >26

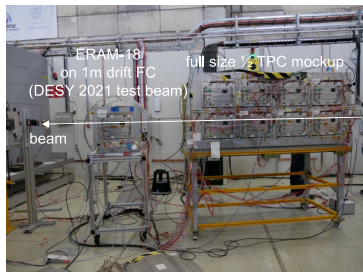


New PCB for ERAM>26



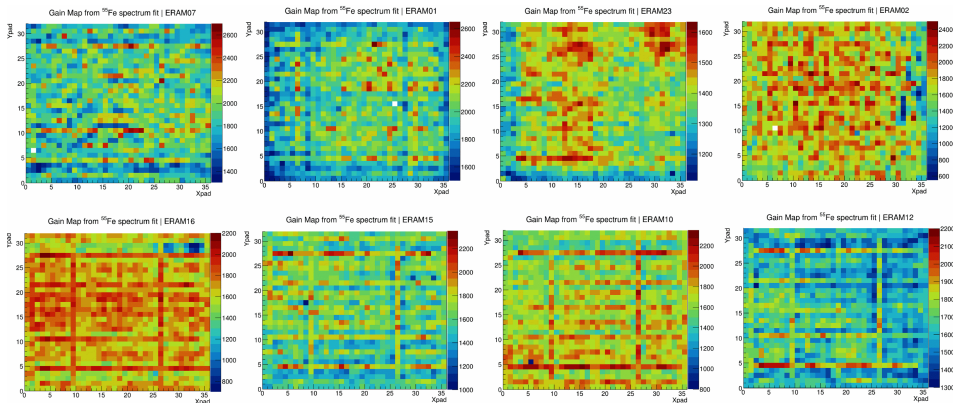
► New PCB design from ERAM-23 \Rightarrow No non-uniformities from mechanics

CERN test beam at PS/T10



- ▶ Field cage with different mechanical and electrical design, 1/2 HA-TPC field cage dimensions
- ▶ 8 final ERAM detectors tested on beam
- ▶ Enabled test and improvement of overall acquisition system
- ▶ 1 prototype field cage equipped with 1 ERAM at different resistivity for ERAM design validation
- ▶ Datasets with different drift distances, ERAM HV, particle types and momenta being analysed

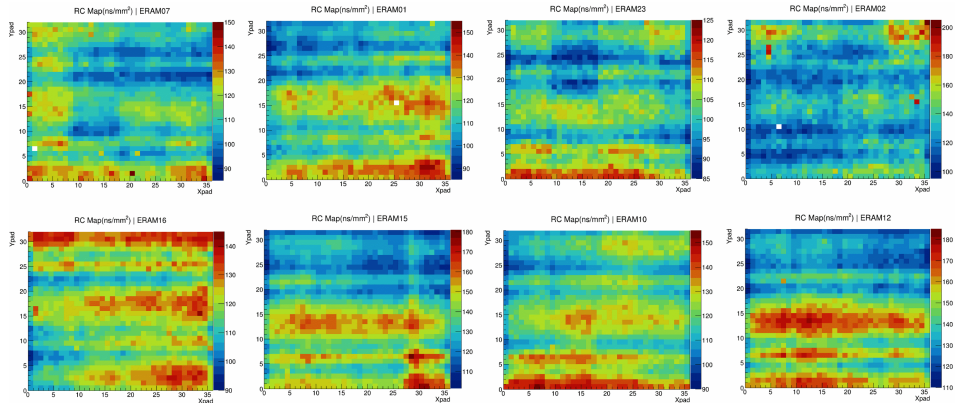
Detector spectrum used at test beam at PS/T10



- ▶ 8 detectors mounted on field cage mock-up in clean room
- ▶ Various PCB designs visible due to mechanics ribs, **not since ERAM-23**
- ▶ Absolute gain of ERAM detectors changes with design
⇒ **under investigation**
- ▶ Effect of **environmental conditions** during gain scan under investigation

RC maps from data

Ref: S. Joshi (IRFU)

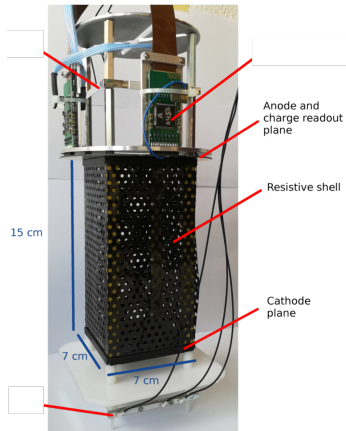


- ▶ RC value extracted from X-ray scans of each ERAM
- ▶ Modelisation of the detector and electronics response implemented
- ▶ RC fitted using the leading and neighbouring pads

Resistive field cage technology

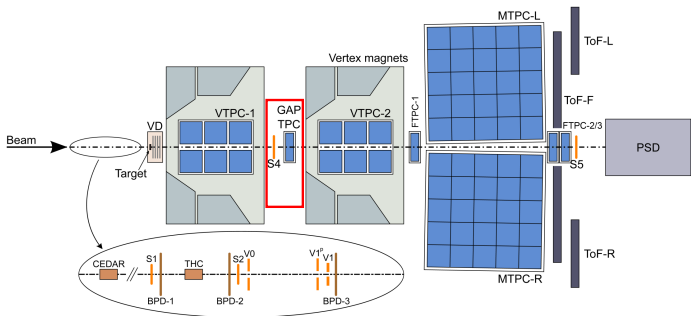
- ▶ Aim: performances improvement for TPC long-term operations
- ▶ Charge readout already exploiting resistive technology
- ▶ Need to be explored for field cages
- ▶ T2K field homogeneity requirement: $\Delta E/E \leq 10^{-4}$ at < 1 cm of cage walls
- ▶ Could be achieved with resistive field cage
- ▶ Voltage degrader requires high resistive foil homogeneity \Rightarrow CERN MPT lab

DUNE-ArgonCube:
Resistive field cage prototype



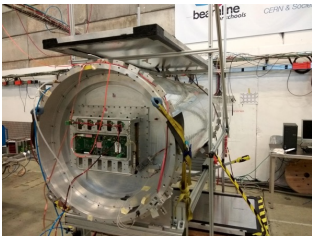
Conclusions

- ▶ Resistive Micromegas inherit from long and successful bulk Micromegas developments
- ▶ Strong interest of CERN for resistive technology
- ▶ Resistive readout shows good performances and large flexibility
- ▶ Highly interesting and promising R&D for resistive field cages



Thank you for your attention!

CERN/T9 2018
MM0/ 1m drift HARP TPC



DESY 2019
MM1-DLC1/15 cm drift



DESY 2021
ERAM-01 / 1 m drift proto FC

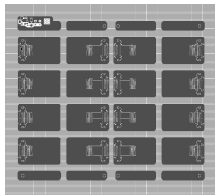
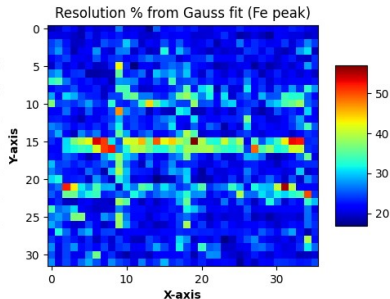
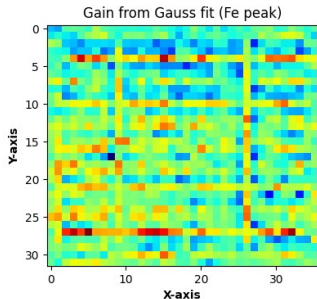


CERN/T10 2022
½ full size TPC with 8 ERAMs

Impact of the PCB design on the gain



ERAM GAIN VS STIFFENER RIBS (ERAM-15)



PCB top layer
black areas are
~20-35 μm thick copper
+ ~50 μm soldermask
(only copper from ERAM-17)
These thicknesses depends
on the PCB manufacturer



A. Delbart, T2K collaboration meeting

Charge diffusion

Charge diffusion function:

$$Q_{pad}(t) = \frac{Q_{norm}}{4} \left[\operatorname{erf} \left(\frac{X_H - X_0}{\sigma(t)\sqrt{2}} \right) - \operatorname{erf} \left(\frac{X_L - X_0}{\sigma(t)\sqrt{2}} \right) \right] \left[\operatorname{erf} \left(\frac{Y_H - Y_0}{\sigma(t)\sqrt{2}} \right) - \operatorname{erf} \left(\frac{Y_L - Y_0}{\sigma(t)\sqrt{2}} \right) \right]$$

- Obtained from Telegraph equation for charge diffusion.
- Integrating charge density function over area of 1 readout pad.
- Parameterized by 4 variables:

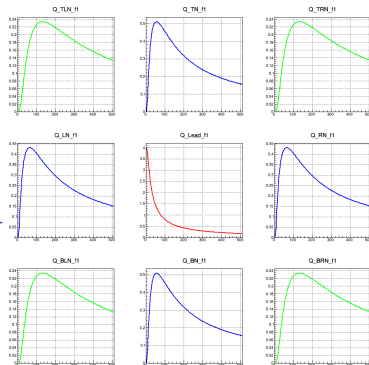
$$\sigma(t) = \sqrt{\frac{2t}{RC}}$$

- X_0 } Initial charge position
- Y_0 }
- RC : Describes charge spreading
- Q_{norm} : Total charge deposited in an event



$$RC = 60 \text{ ns/mm}^2$$

$$Q_{norm} = 4 \text{ ADC}$$

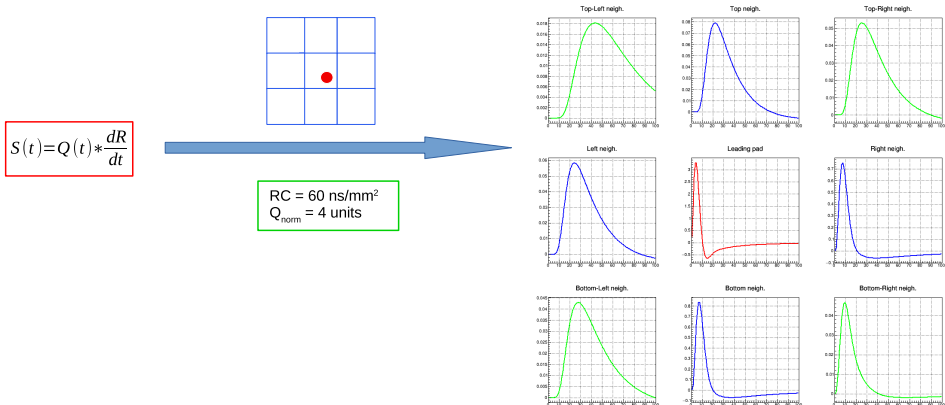


x_H, x_L : Upper and lower bound of a pad in x-direction
 y_H, y_L : Upper and lower bound of a pad in y-direction

S. Joshi, talk at IRN Neutrino 2022

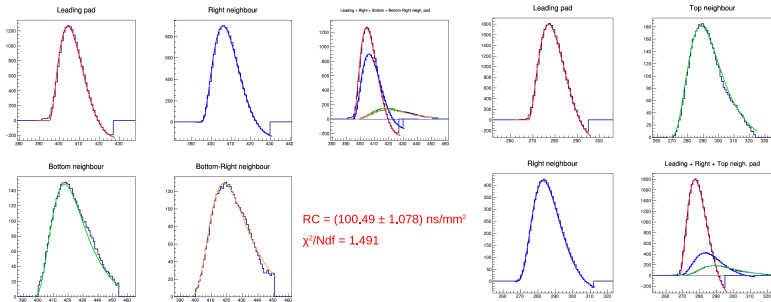
Signal Model

- Convolution of charge diffusion function with derivative of electronics response function.



S. Joshi, talk at IRN Neutrino 2022

RC extraction



$RC = (110.82 \pm 1.363) \text{ ns/mm}^2$
 $\chi^2/\text{Ndf} = 1.903$

$RC = (100.49 \pm 1.078) \text{ ns/mm}^2$
 $\chi^2/\text{Ndf} = 1.491$

4-waveform simultaneous fit of an X-ray event

3-waveform simultaneous fit of an X-ray event

- RC is obtained for a pad by simultaneous fit of waveforms in each event.

S. Joshi, talk at IRN Neutrino 2022